## Rupture, Fracture and size issues

#### E. Barthel

Surface du Verre et Interfaces

2010 / Mecano



## Lignes directrices

The ultimate downscaling...Theoretical strength(s) Theoretical tensile strength

Energy picture – Brittle and semi-brittle fracture General considerations Downscaling

Stress concentration and Process zone – Plastic deformation at the crack tip

- Stress distribution around the crack tip
- Process zone and downscaling



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### Rigid surfaces - the Orowan estimate

Assume loading *on* surfaces

$$\sigma(z) = E \frac{z}{\Delta}$$
$$V_{el}(z)/A = E \frac{z^2}{2\Delta} = \frac{\sigma^2 \Delta}{2E}$$

Rupture occurs when  $\sigma(z_{rupt}) \equiv \sigma_{theo}$  is such that  $V_{el} \simeq w$ 

$$\sigma_{theo} \simeq \sqrt{\frac{2Ew}{\Delta}} \tag{1}$$

After Lawn 1975 [1]



Figure: Interaction energy as a function of surface separation



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or 100 tons =  $10^6$  N on  $1{\times}1~\text{cm}^2$  !!!





- $1. \ \mbox{gravity}$  against surface forces
- 2. balance gives surface win if

$$R^2 < w/
ho g$$

3. Cut-off radius around 1 mm !!!



Figure: A typical MEMS

There is something more to it...roughness



## What if remote loading ?





Figure: Stress

From Pedone 2008 [2]



### Assuming remote loading ...

- the stress is homogeneous through the macroscopic body
- predicts simultaneous rupture of the full volume when

$$\sigma_{theo} \simeq \sqrt{\frac{2Ew}{\Delta}}$$

#### Problem

- 1. Rupture does not (usually) happen that way ightarrow localized
- 2. We need to examine the loading and the stress distribution



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#### Problem

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## Similar estimates for theoretical shear strength

• voir les cours de Benoit Devincre et Marc Legros



## Can we measure the theoretical tensile strength directly ?

- 1. Surface forces measurements with fine tips allow for direct measurement of local inter-surface interactions
- 2. note long range contribution



After Lanz 2001 [3]



#### More sophisticated...

With long range cohesive forces

$$\begin{array}{rcl} \sigma(z) &=& Az \mbox{ for } z \ll \Delta \\ \sigma(z) &=& Cz^{-3} \mbox{ for } z \gg \Delta \end{array}$$

Rupture occurs when  $\sigma(z_{rupt}) \equiv \sigma_{theo}$  is of the order

$$\sigma_{crit} \simeq (A^{1/3}C)^{1/4}$$

Ref. Kohn 1979 [4]



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## Fracture: the energy release rate

### Bottom line

- A very unstable geometry : fracture
- How much energy is available ? = stability criterion for the fracture



Figure: A crack with some remote loading.



## Energy Release Rate – Peeling

• Energy balance:

-F da = -w b da

• Energy release rate:

$$\mathcal{G} = F/b = w$$



Figure: Peeling at 90°.

- No elastic deformation energy
- simplest example ever



## Energy release rate – Calculation

A bit of technique

Method

- equilibrium solution including co/ad-hesive energy
- from potential energy minimization



# Potential Energy Minimization A 1-element model

- from potential energy minimization
- a simple example

$$\mathcal{E} = \frac{k}{2}(u - u_0)^2 - uF$$
$$d\mathcal{E} = k(u - u_0)du - duF$$



Figure: A simple spring system under tension.

#### Equilibrium

The equilibrium value of u obeys  $d\mathcal{E} = 0$  for all du or

$$F = k(u - u_0)$$



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#### Energy release rate – Energy balance

- from potential energy minimization
- fracture: general case

$$\mathcal{E} = \mathcal{E}_{el} - \left\{ \int_{surf} u\sigma dS \right\}$$
$$d\mathcal{E} = 0$$



Figure: Schematics of the cohesive zone

Contribution from the cohesive stresses  $d\left\{\int_{surf} u\sigma dS\right\} = \int_{0}^{\infty} \sigma_{coh}(z) dz dA = w dA$ SAINT-GOBAIL

#### Energy release rate – Energy balance

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#### Bottom line

 Energy release rate – working definition

$$\mathcal{G} \equiv \left. \frac{d\mathcal{E}_{el}}{dA} \right|_{\delta}$$

or

$$\mathcal{G} \equiv \left. \frac{d(\mathcal{E}_{el} - F\delta)}{dA} \right|_F$$

• At equilibrium

$$\mathcal{G} = w$$



 $\label{eq:Figure: Figure: A crack with some remote loading.} % \label{eq:Figure: Figure: Fig$ 



A non-trivial example – the Double Cantilever Beam

$$F = \alpha \delta$$
 with  $\alpha = \frac{Eb}{4} \left(\frac{h}{L}\right)^3$   
 $\mathcal{E}_{el}(\delta, A) = \frac{1}{2} \alpha \delta^2$ 



#### Energy release rate

$$\mathcal{G} = \frac{3Eh^3}{8} \frac{\delta^2}{L^4} \text{ at fixed grip}$$

and

$$\mathcal{G} = rac{6}{Eh^3}L^2\left(rac{F}{b}
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 at fixed load

AIN

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AIN

- fixed grip is isochoric
- fixed load is isobaric



of Mauric 2000 [E]

## double cantilever beam – Application

#### thin film adhesion

- glass substrate and backing
- multilayers deposited on the substrate



#### Interface toughness measurements



Figure: Application of DCB test for thin film adhesion measurements.

After Barthel 2005 [6]

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#### Crack branching - the Cook Gordon mechanism

$$\sigma = \sqrt{\frac{E^* w_{coh}}{\pi h}}$$
 and  $\sigma = \sqrt{\frac{4Ew_{int}}{h}}$  (2)



Figure: Branching criterion for coating fracture.



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Figure: Branching criterion for coating fracture.

Interface delamination  $w_{coh} > 4\pi w_{int}$ SAINT-GOBAIN

## Energy release rate – the general case

#### Full 3D fracture

Energy release rate:

$$\mathcal{G} = \psi \frac{\sigma^2 a}{F}$$

where  $\psi$  is a numerical constant of the order of 1



Figure: A 3D crack – half-penny.



## Energy release rate – the general case

#### Full 3D fracture

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Figure: A 3D crack – half-penny.



## Size effects in rupture



After Griffith 1921 [7]





After Telford, Materials Today, March 2004.





Ultimate tensile strain 99 90 80 E-glass 60 *m*=119 Cumulative failure probability (%)  $\epsilon_{avg}$ =12.81% 40 20 10 Silica 5 *m* = 103 3  $\varepsilon_{avg} = 17.98\%$ 12 16 17 18 19 20 9 10 11 13 14 15 Failure strain (%)

Figure: Rupture strain distribution for glass and silica fibers.



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After Brow 2005 [8]



After Lin 1996 [9]





After Namazu 2000 [10]

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displacement:

$$w=\frac{Ed^2}{2h}$$

mean stress

$$\sigma = \sqrt{\frac{2Ew}{h}} \quad (4)$$



Figure: Punch on a thin film

The glue salesman paradox (Kendall 2001 [11]) The less glue the more it sticks (*ie* the larger the pull-out force)

<sup>1</sup>The energy at rupture  $\int Fdd = w$  but is difficult to measure (institution stiffness)

#### Experimental results

- 1. Pull out test on cylindrical dies
- 2. Variable glue joint thickness



After Kendall 2001 [11]



Energy release rate  
a) 
$$\mathcal{G} = \psi_0 \frac{\sigma^2 a}{E}$$
  
b)  $\mathcal{G} = \psi_1 \frac{\sigma^2 h}{E}$ 



Figure: Substrate constraint on thin films.

After Cook 2002 [12]



#### Impact of substrate constraint - compliant interlayer



After Tsui 2005 [13]



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## Antiplane elasticity

Same quality, lower price...

### Elastic fields and equilibrium

deformation and stress

$$\bar{\epsilon} = \nabla u(x, y)$$

$$\bar{\sigma} = \mu \bar{\epsilon}$$

• equilibrium

$${
m div}(ar{\sigma})=2\mu riangle(u)$$
  
 $\Delta u=0$ 



Figure: Deformation for antiplane elasticity



## Boundary conditions

#### Boundary conditions

stress

$$\sigma_y = 0$$
 for  $\theta = \pm \pi$ 

• *u* is discontinuous on the fracture faces



Figure: Fracture geometry in mode III



$$u = \mathcal{I}m(\Omega)$$
 with  $\Omega = Az^{1/2}$ 



Figure: The stress distribution around the crack tip.

$$\sigma_x = -A\mu/2r^{-\frac{1}{2}}\sin(\theta/2)$$
  
$$\sigma_y = A\mu/2r^{-\frac{1}{2}}\cos(\theta/2)$$



## Direct Measurement of Stress-Intensity Factor



Figure: Measured crack tip stress field. After Coo



## Connexion to the macroscopic lengthscale

With  $K = A\mu$  $\mathcal{G} = \frac{\pi}{2} \frac{K^2}{2\mu}$ 



## The lower lengthscale problem

$$\sigma_{coh} \simeq \sqrt{\frac{Ew}{\epsilon}}$$
 (5



 $\label{eq:Figure: Cohesive stress and singularity regularization / Barenblat-Dugdale model$ 



## The lower lengthscale problem







## The lower lengthscale problem





After Arzt 2003 [14]



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Rupture and macroscopic plasticity

- plastic dissipation contributes to the (steady state) effective toughness Γ<sub>ss</sub>
- extends over radius R<sub>ss</sub>
- yield stress:

$$\sigma_y \simeq \sqrt{\frac{\Gamma_{ss}E}{R_{ss}}} \qquad (6)$$



Figure: Two models for plastic dissipation



After Wei 1999 [15]



From Wei 1999 [15]



## Toughness as a function of confinement ĸ<sub>ic</sub> Τh 10-9 10-6 10-3 r<sub>p</sub> h (meters) Figure: Three regimes of confinement. From Hsia 1994 [16]

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- Cu film
- Mao model based on [16]
- Present model based on:

$$\sigma_y = \sigma_{y0} \left( 1 + \frac{\beta}{\sqrt{h}} \right)$$

## Contribution of plastic dissipation



From Volinsky 2002 [17]



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#### Tensile strength of Cu whiskers

From Brenner 1956 [19]



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#### MR. A. A. GRIFFITH ON

In 1858, KARMARSCH\* found that the tensile strength of metal wires could be represented within a few per cent. by an expression of the type

$$\mathbf{F} = \mathbf{A} + \frac{\mathbf{B}}{d}$$
 . . . . . . . . . . (22)

where d is the diameter and A and B are constants.

#### From Griffith 1921 [7]



## Conclusion

#### Rupture

Beyond the physical rupture mechanisms at the interface

- intrinsically spans lengthscales
- intrinsically spans stress ranges
- involves specific material response





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